Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

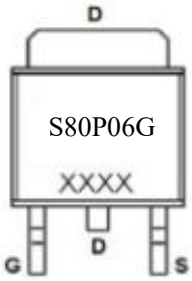
Bvdss	Rdson	ID
-60V	9mΩ	-80A

Application

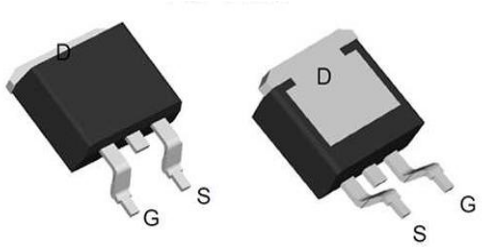
RoHS

- DC-DC Converters
- Synchronous-rectification applications
- Power management functions

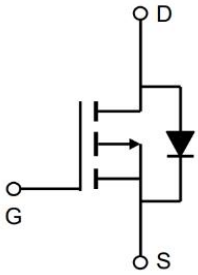
Package



Marking and pin assignment



TO-263 top view



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Quantity
80P06	S80P06G	TO-263	800

Absolute Maximum Ratings (T_J=25℃ unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-60	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25° C	I_D	-80	A
	T_C=100° C	I_D	-50	A
Pulsed Drain Current		I_{DM}[1]	-320	A
Single Pulse Avalanche Energy		E_{AS}[2]	450	mJ
Power Dissipation	T_C = 25℃	P_D	110	W
Operating junction and storage temperature		T_J, T_{STG}	150, -55 ~ 150	℃
Maximum Temperature for Soldering		T_L	300	℃

Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Case	$R_{\theta JC}$	1.1	℃/W
Thermal Resistance, Junction -to-Ambient	$R_{\theta JA}$	60	℃/W

Ordering Information

Ordering Number	Package	Pin Assignment			Packing
Halogen Free		G	D	S	
HLS80P06G	TO-263	1	2	3	Tape Reel

Electrical Characteristics (Tj=25℃ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D = -250μA	-60	-	-	V
Gate-body Leakage current	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -60V, V_{GS} = 0V	-	-	1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS} =V_{GS} , I_D = -250μA	-1.3	-1.8	-2.3	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = -10V, I_D = -20A	-	9	11	mΩ
		V_{GS} = -4.5V, I_D = -15A	-	12	16	
Forward Transconductance	g_{fs}	V_{DS} = -5V, I_D = -20A	50	-	-	S
Input Capacitance	C_{ISS}	V_{DS} = -30V,V_{GS} =0V, f =1MHz	-	3060	-	pF
Output Capacitance	C_{OSS}		-	620	-	
Reverse Transfer Capacitance	C_{RSS}		-	20	-	
Gate Resistance	R_g	V_{GS}=0V, V_{DS} Open	-	2	-	Ω
Total Gate Charge	Q_g	V_{GS} = -10V,V_{DS} = -30V, I_D = -20A	-	56	-	nC
Gate-Source Charge	Q_{gs}		-	11	-	
Gate-Drain Charge	Q_{gd}		-	9	-	
Turn-On Delay Time	$T_{d(on)}$	V_{GS} = -10V, V_{DS} = -30V, R_G = 3Ω, I_D = -20A R_L = 0.75Ω	-	4.5	-	ns
Rise Time	T_R		-	2.5	-	
Turn-Off Delay Time	$T_{d(off)}$		-	14.5	-	
Fall Time	T_F		-	3.5	-	
Diode Forward Current	I_S	T_C=25℃	-	-	-80	A
Diode Pulse Current	I_{SM}		-	-	-320	A
Diode Forward Voltage	V_{SD}	I_S=-6A, V_{GS}=0V	-	-	-1.2	V

Reverse Recovery time	T_{rr}	I_S=-20A, V_{DD}=-30V	-	60	-	ns
Reverse Recovery Charge	Q_{rr}	dI/dt=100A/μs	-	105	-	nC

Note :

1.Repetitive rating; pulse width limited by maximum junction temperature

2.V_{DD} =30V, L=0.3mH, R_G =25Ω, Starting T_j=25℃

Typical Performance Characteristics

Fig1:Typ. output characteristics

I_D=f(-V_{DS})

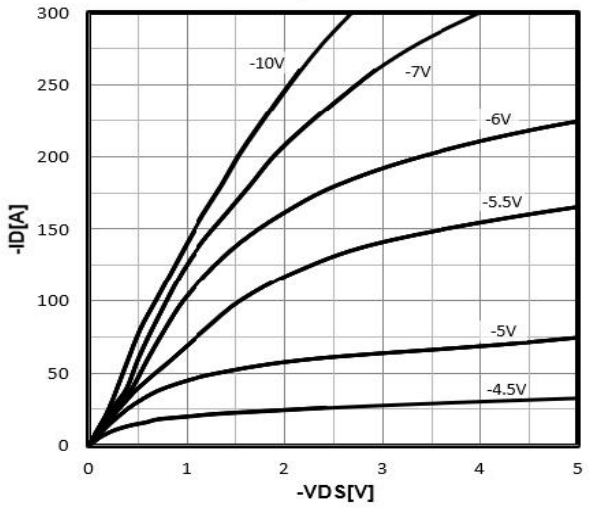


Fig2:Typ. drain-source on resistance

$R_{DS(on)}$=f(-I_D)

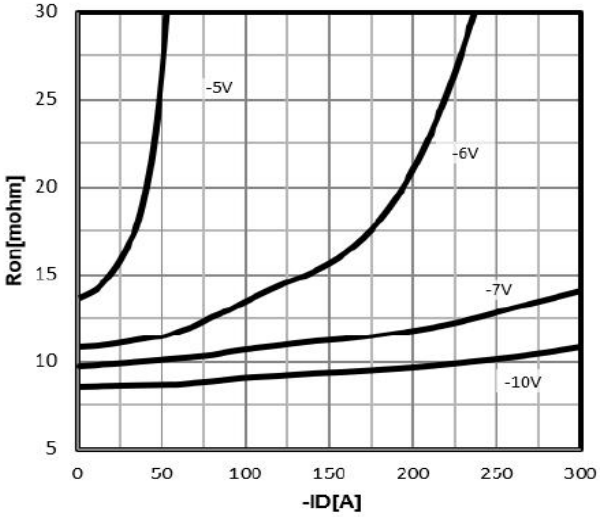


Fig3:Typ. transfer characteristics

-I_D=f(-V_{GS}) ;

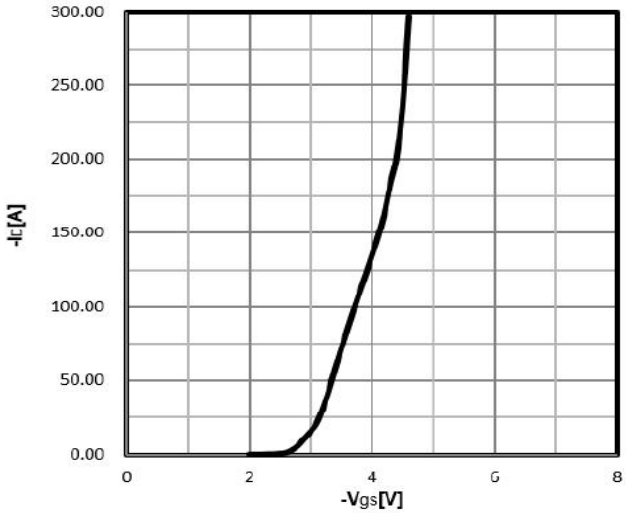


Fig4:Typ. forward transconductance

g_{fs}=f(I_D)

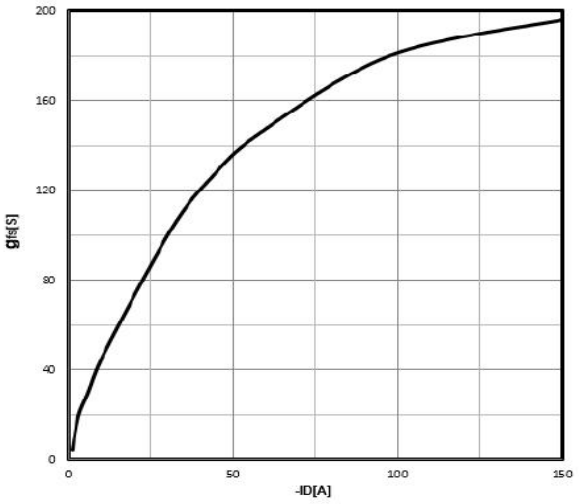


Fig5:Drain-source on-state resistance

$R_{DS(on)}=f(T_j)$; I_D=-20A; V_{GS}=-10V ;

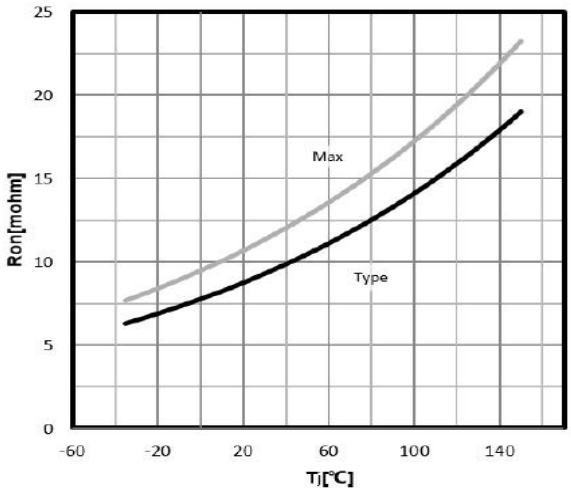


Fig6:Typ. capacitances

C =f(V_{DS}); V_{GS}=0V; f =1MHz ;

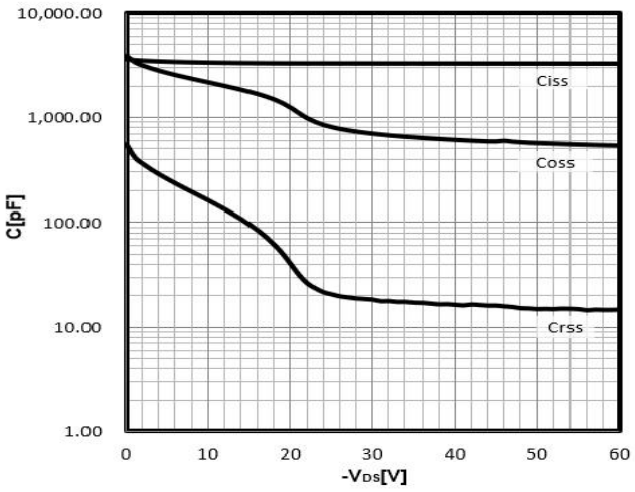


Fig7:Typ. gate charge

V_{GS}=f(Q_g), I_D=-20A;

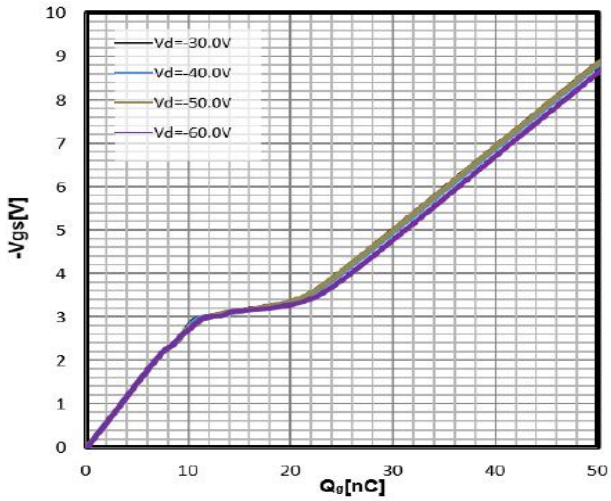


Fig8:Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j)$; I_D=-250uA ;

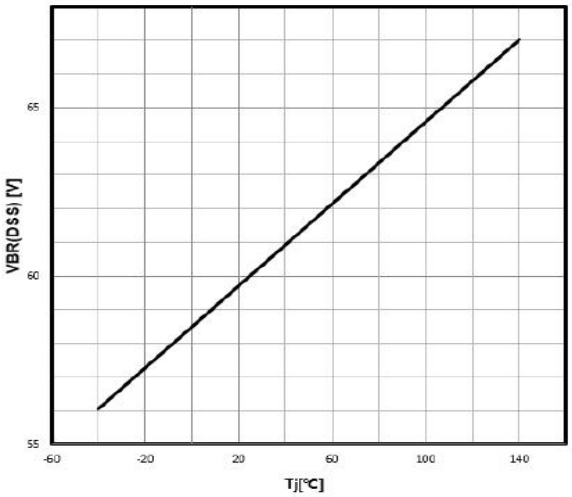


Fig9:Power Dissipation

$P_{tot}=f(T_C)$

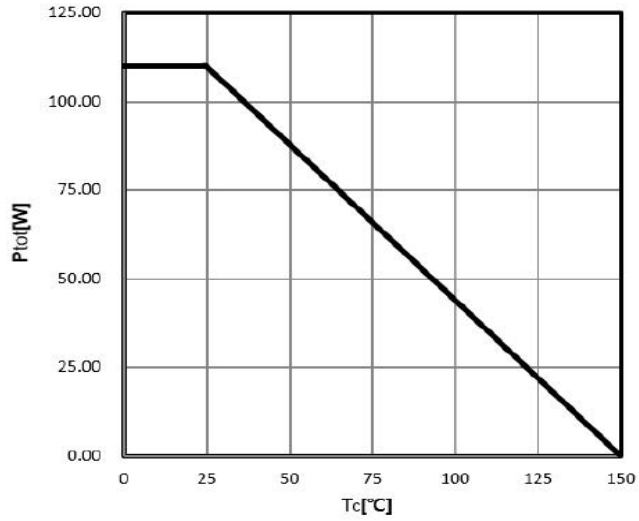


Fig10:Safe operating area

$I_D=f(V_{DS})$

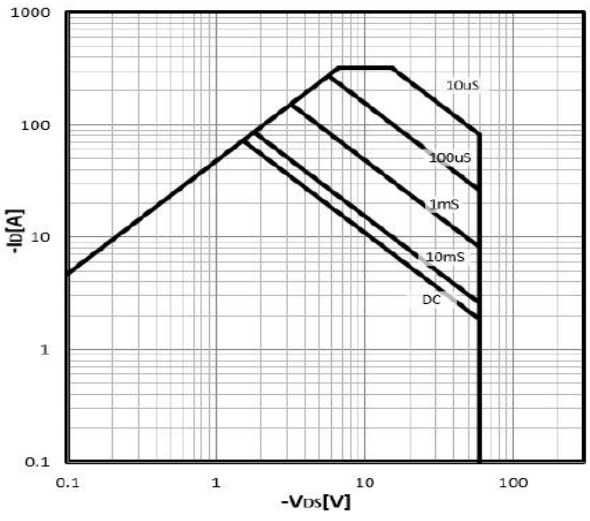
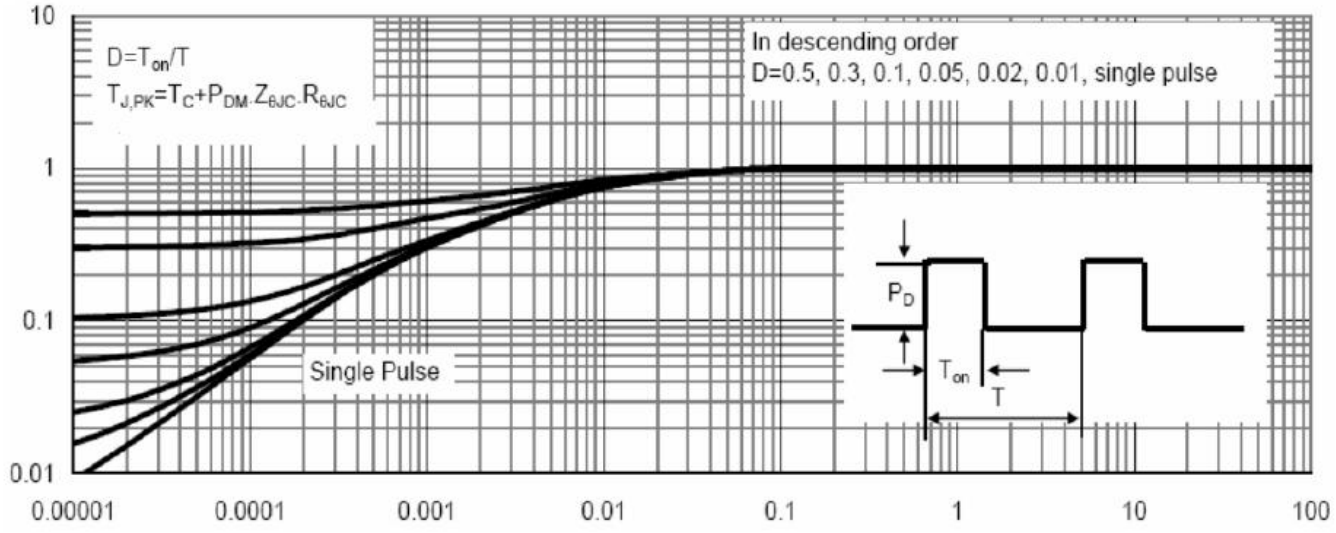
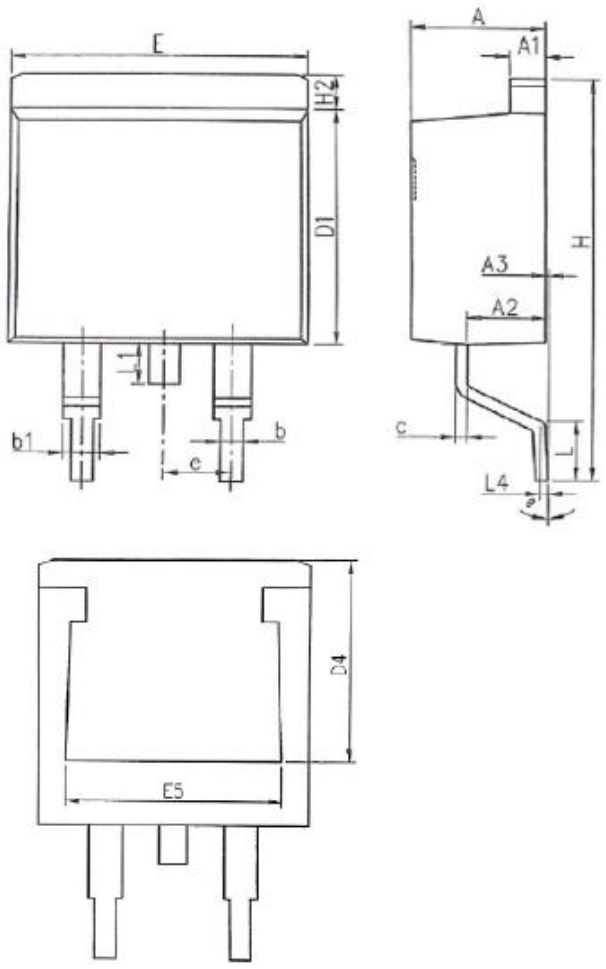


Figure 11: Max. Transient Thermal Impedance

$Z_{thJC}=f(t_p)$



Package Dimensions TO263



COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

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